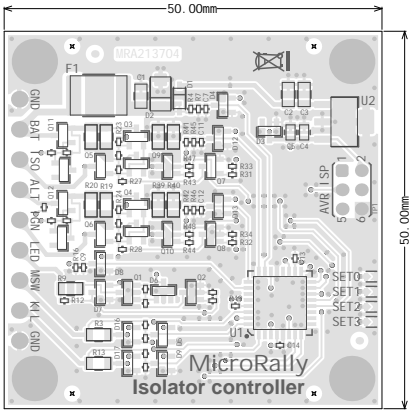
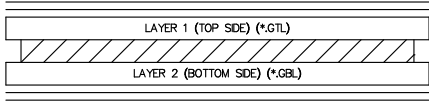


# GERBER NOTES

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
⊕	265	0.300mm	PTH	Round	Via
▽	6	1.000mm	PTH	Round	Pad
✕	4	1.152mm	NPTH	Round	Pad
⊛	9	1.300mm	PTH	Round	Pad
○	4	3.600mm	PTH	Round	Pad
	288 Total				



1.0 OZ L1  
1.50 mm Core – FR4  
1.0 OZ L2



PASTE (TOP SIDE) (\*GTP)  
SILKSCREEN (TOP SIDE) (\*GTO)  
SOLDERMASK (TOP SIDE) (\*GTS)  
1.6 mm +/- 10%  
LAYER DETAIL  
2 LAYERS  
SOLDERMASK (BOTTOM SIDE) (\*GBS)  
SILKSCREEN (BOTTOM SIDE) (\*GBO)

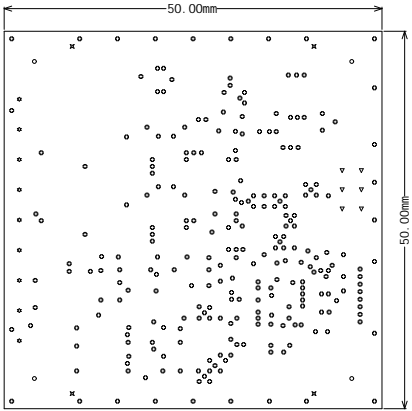
## NOTES: (UNLESS OTHERWISE SPECIFIED)

- THIS IS 2 LAYER BOARD
- MATERIAL: FR4, TG 150 DEGREE C MIN
- FR4 DIELECTRIC CONSTANT NOT SPECIFIED
- FINISHED BOARD THICKNESS TO BE 1.60MM +/- 10%
- TRACE WIDTHS IN ARTWORK ARE FINISHED SIZES
- SEE FILM FOR LAYER SEQUENCE AND COPPER THICKNESSES (SHOWN BEFORE PLATING)
- MIN TRACE/SPACE 0.25/0.25MM
- SEE DRILL CHART FOR FINISHED HOLE SIZES
- MIN DRILL 0.30MM
- HOLE TOLERANCE IS +/-3MIL UNLESS OTHERWISE SPECIFIED  
HOLE COPPER THICKNESS MIN 0.7MIL  
SLOT TOLERANCE +/-0.1MM  
BORDER OUTLINE TOLERANCE +/-0.15MM
- SURFACE PLATING: HASL, Pb FREE
- SOLDERMASK: LPI, BOTH SIDES. COLOR GREEN
- SILKSCREEN: TOP AND BOTTOM SIDE. COLOR WHITE
- ALL BOARDS MUST BE ELECTRICALLY TESTED FOR ISOLATION (SHORTS) AND CONTINUITY (OPENS)

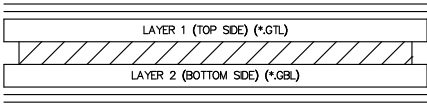
Project: Isolator Controller	
Author: Andis Jargans	Revision: 4
Date: 15.09.2021	Size: A4
File: Isolator_controller_r4.PcbDoc	MicroRally

# GERBER NOTES

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288 Total					



1.0 OZ L1  
1.50 mm Core – FR4  
1.0 OZ L2



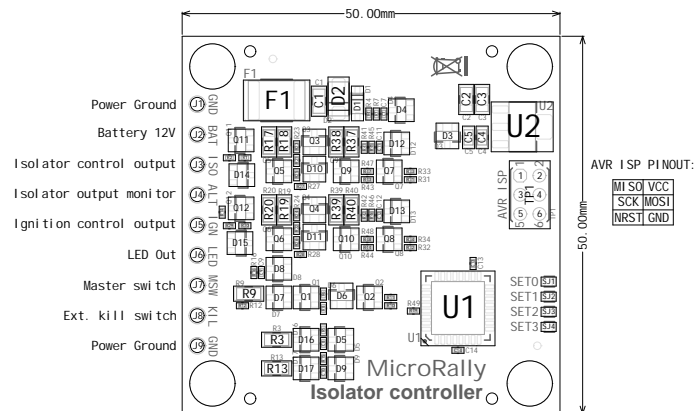
PASTE (TOP SIDE) (\*GTP)  
SILKSCREEN (TOP SIDE) (\*GTO)  
SOLDERMASK (TOP SIDE) (\*GTS)  
1.6 mm +/- 10% LAYER DETAIL 2 LAYERS  
SOLDERMASK (BOTTOM SIDE) (\*GBS)  
SILKSCREEN (BOTTOM SIDE) (\*GBO)

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Project: Isolator Controller	
Author: Andis Jargans	Revision: 4
Date: 15.09.2021	Size: A4
File: Isolator_controller_r4.PcbDoc	MicroRally

# ASSEMBLY NOTES



## Bootstrap settings:

SET0 to SET4 are solder jumpers. Connect necessary jumper pads with lump of solder. Refer to datasheet for functions.

## LED brightness:

Use R37 to control LED current and thus brightness.

If LED has built-in LED, then replace R37 with 0 ohm resistor.

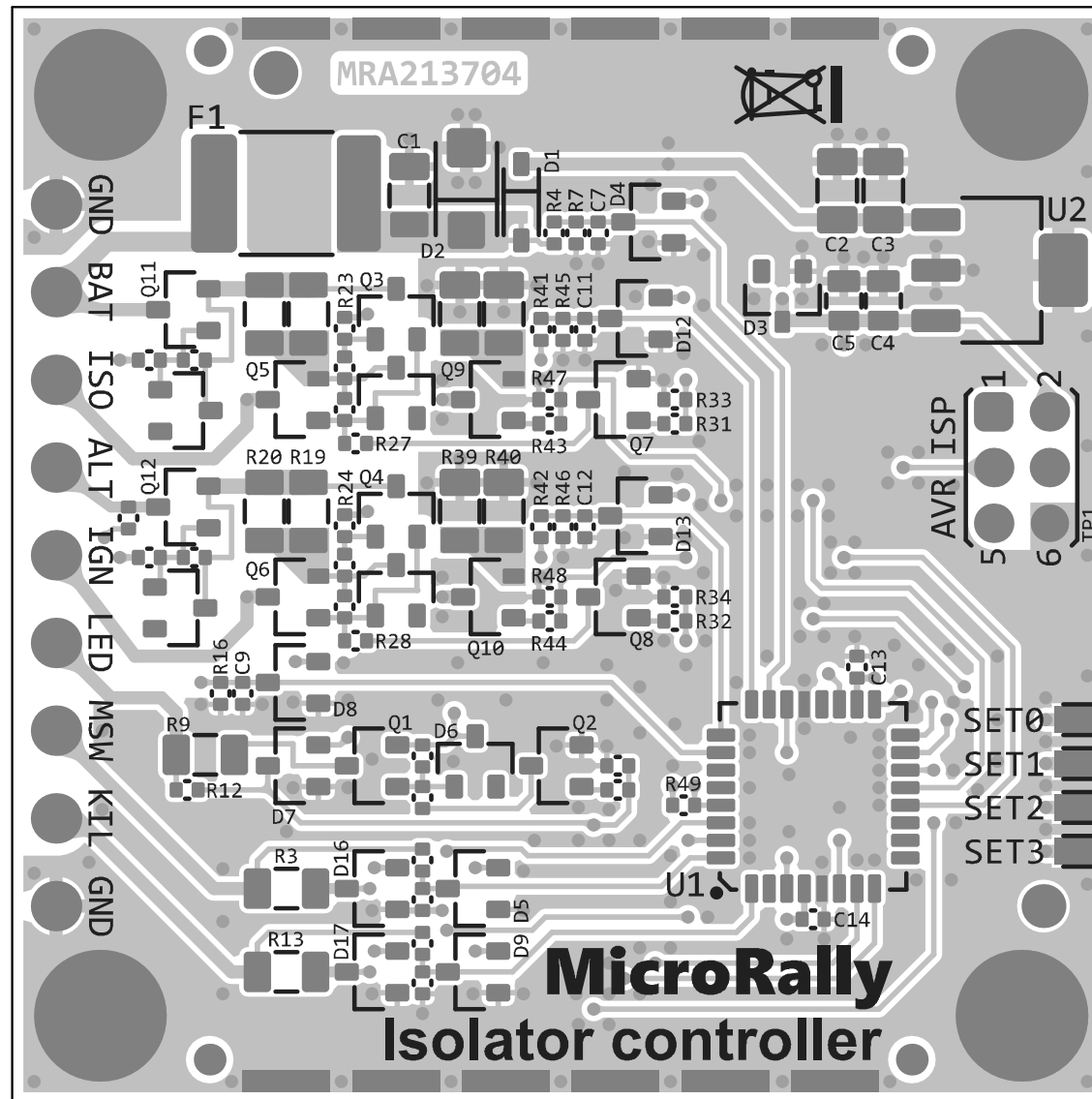
## LED power source

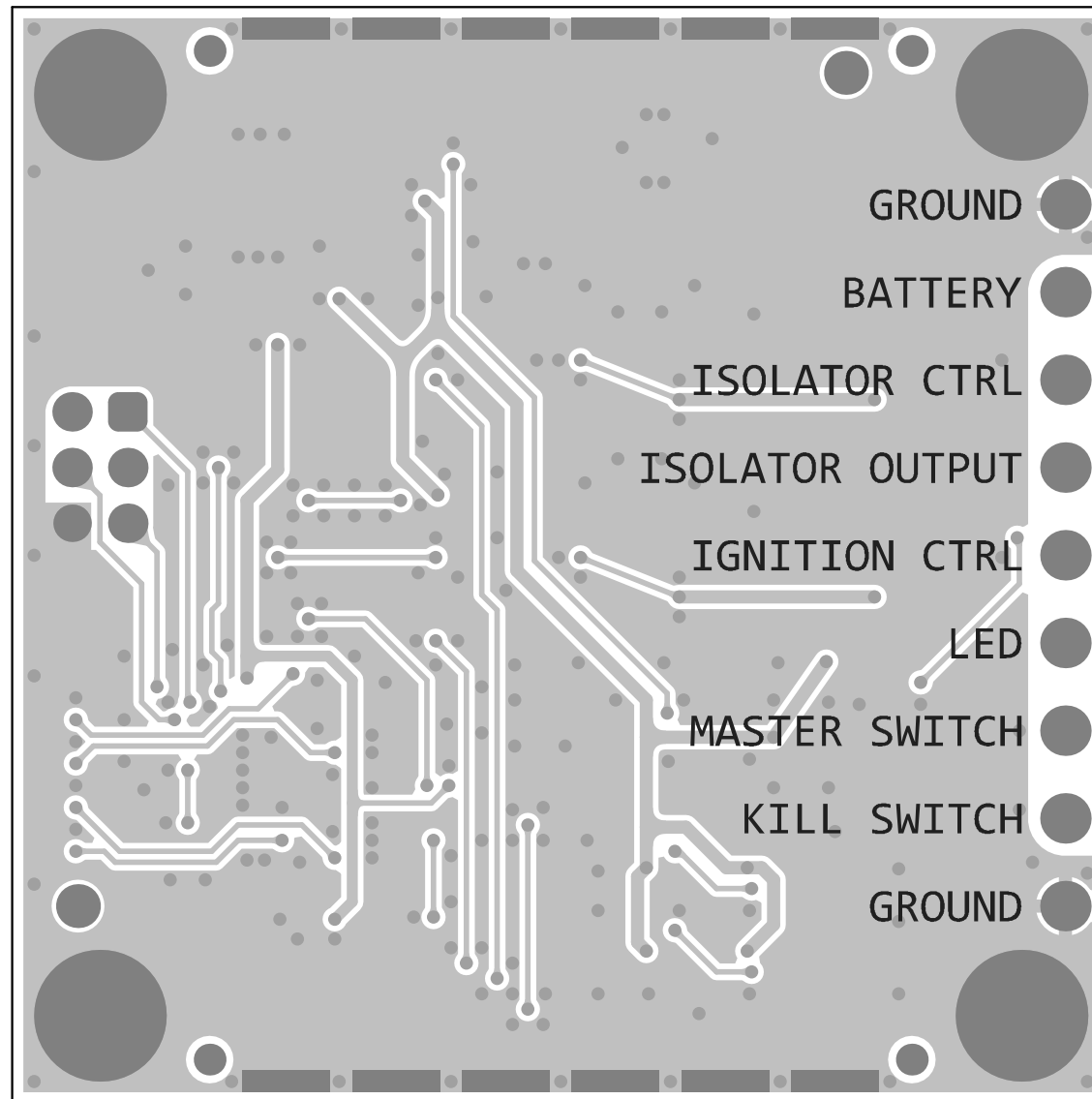
To control LED directly from MCU GPIO:

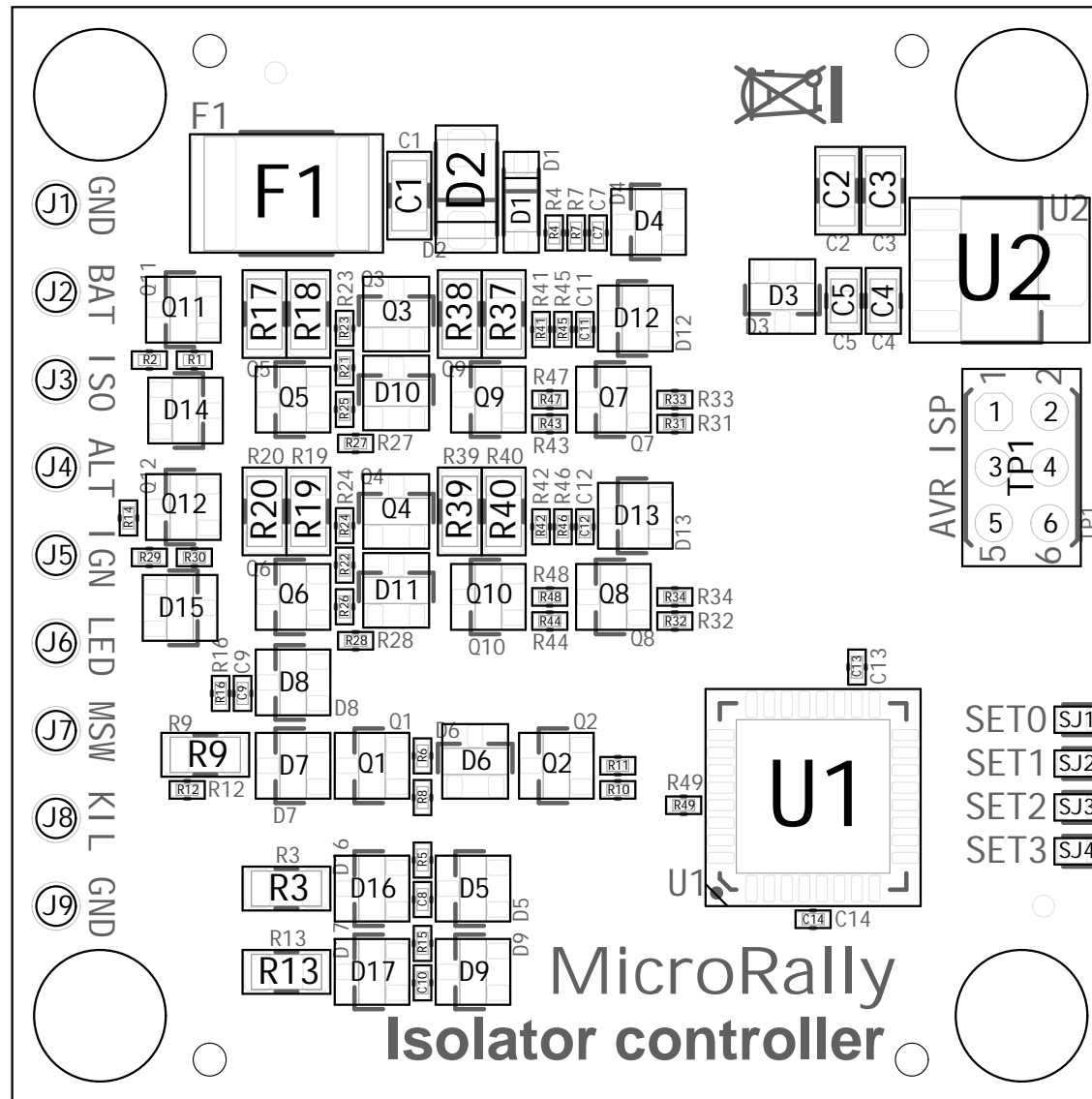
Load R40, D12. Not-load R37, Q9, Q10, D11.

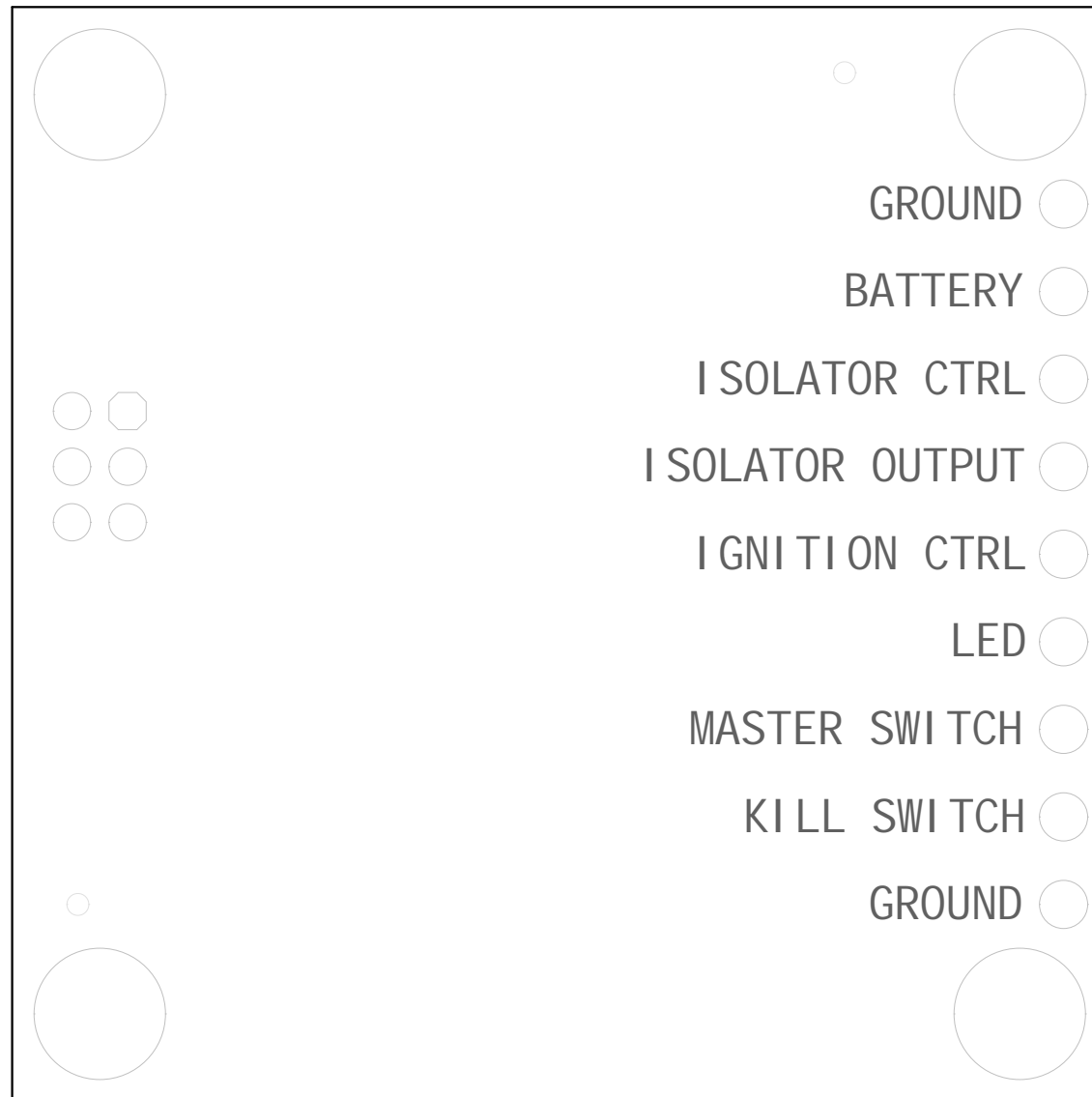
Use R40 to control LED current.

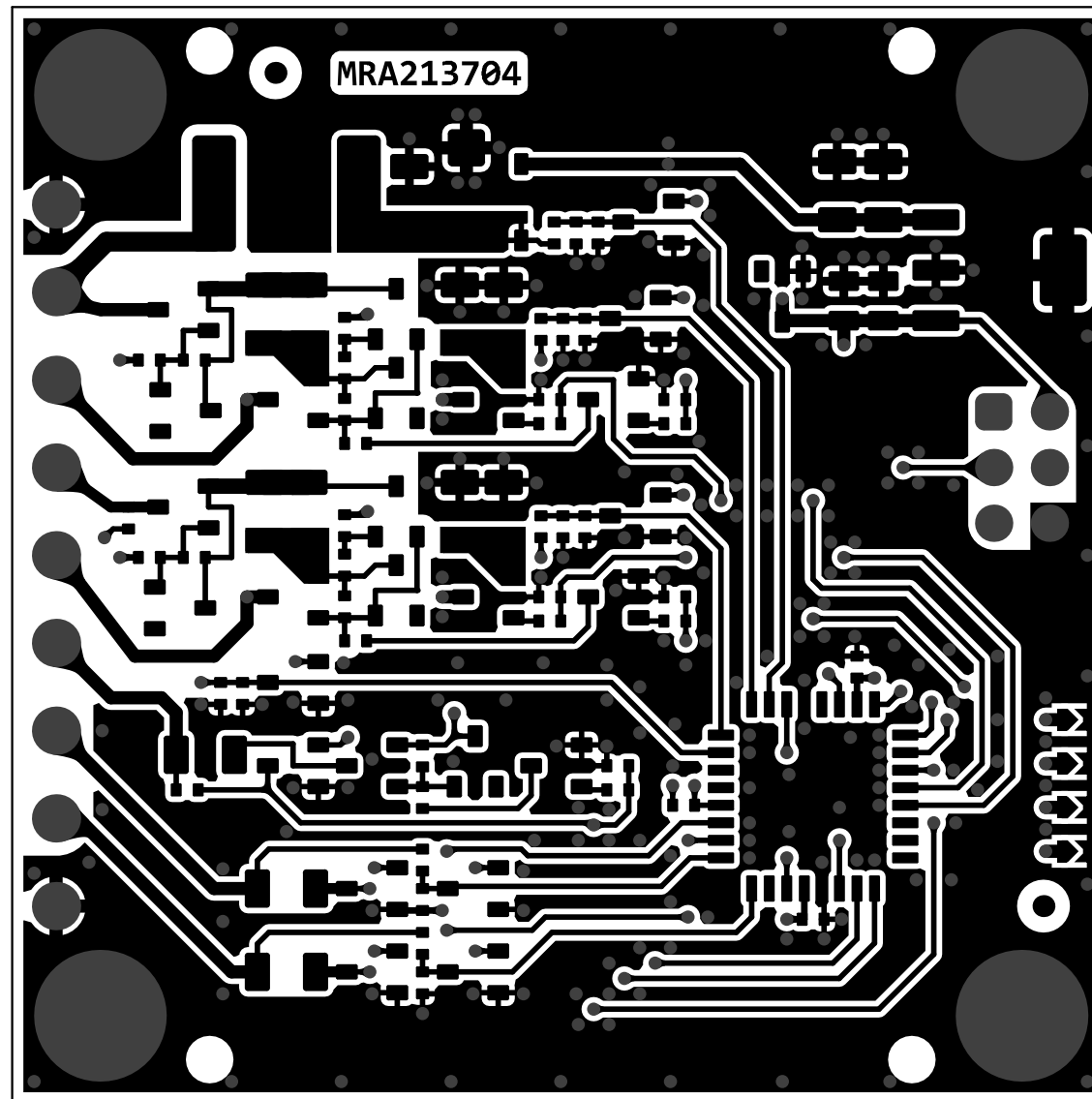
Project: Isolator Controller	
Author: Andis Jargans	Revision: 4
Date: 15.09.2021	Size: A4
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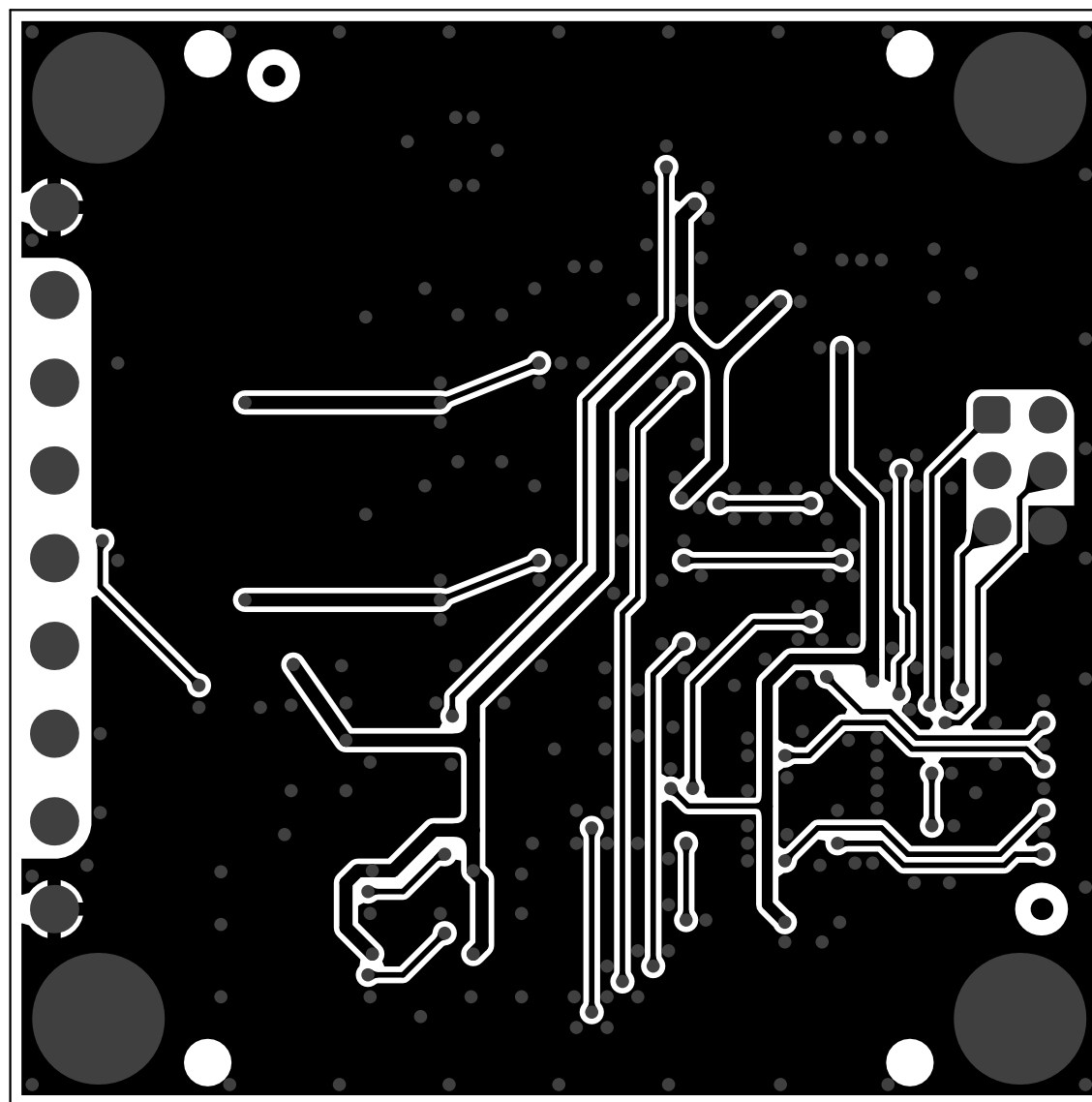




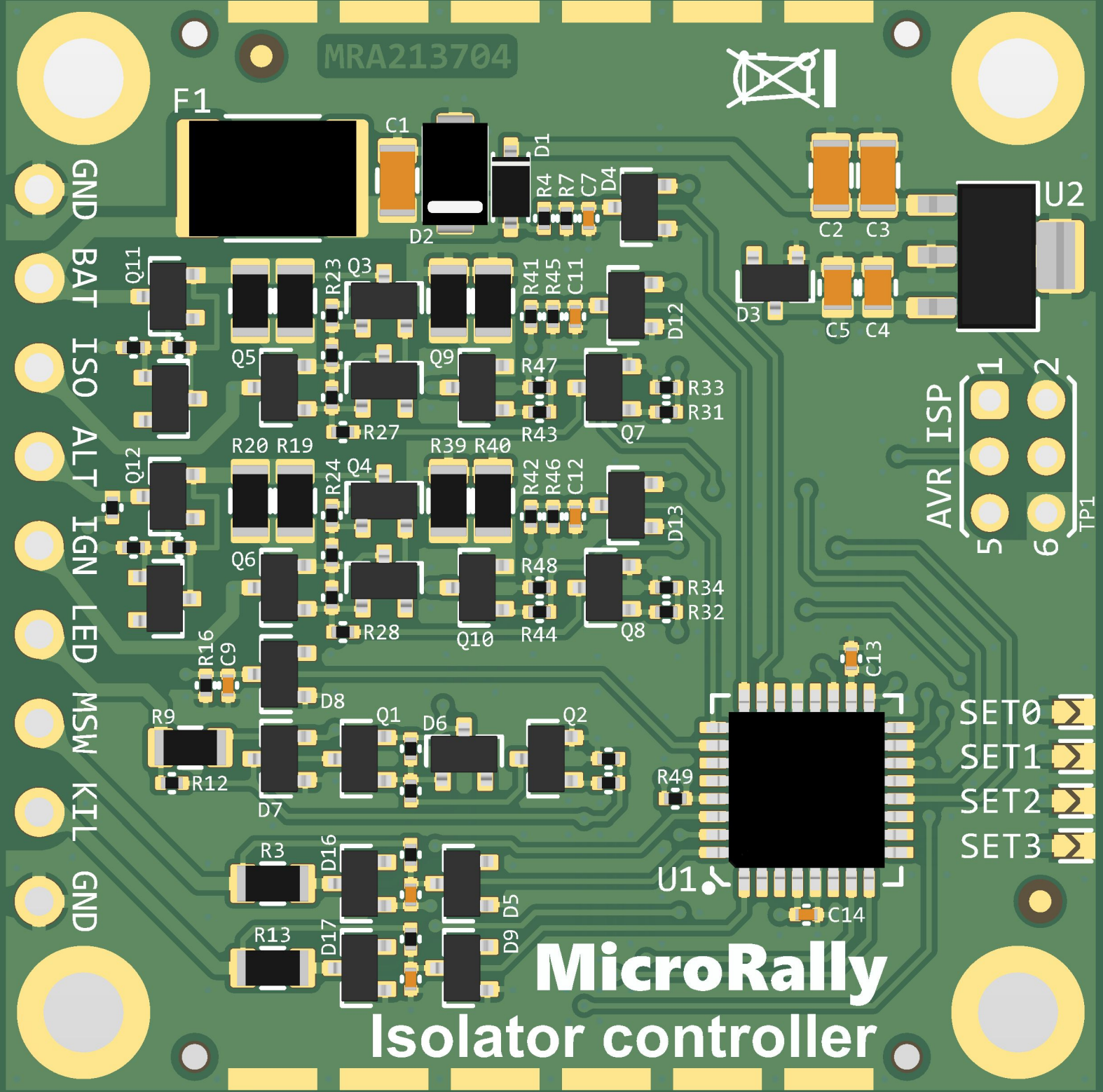








MRA213704



GND  
BAT  
ISO  
ALT  
IGN  
LED  
MSW  
KIL  
GND

AVR ISP  
1 2  
5 6  
TP1

SET0  
SET1  
SET2  
SET3

**MicroRally**  
Isolator controller

